

Special Issue

Flexible/Stretchable Electronics and Devices

Message from the Guest Editor

Recently, flexible/stretchable electronics attract a great deal of attention due to their potential application in various next-generation electronic devices (e.g., wearable health care systems, Internet of Things systems, energy-harvesting/storage devices). Electronic devices consist of various components, which require different strategies to make them be flexible or stretchable. The development of novel materials compatible with flexible/stretchable systems is one of the main research areas in flexible/stretchable electronic systems, focusing mostly on composites consisting of stretchable matrix and conducting fillers. Structural design to make rigid systems flexible or stretchable by geometry change is also considered a promising method for flexible/stretchable electronics. Accordingly, this Special Issue seeks to showcase research papers and review articles that focus on the development of materials or systems for flexible/stretchable electronics. Readers will be provided with a comprehensive understanding and perspective on flexible/stretchable electronics:

- flexible electronics
- stretchable electronics
- electrode
- interconnect
- device

Guest Editor

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